

INTEGRATED CIRCUIT PACKAGE AND METHOD

Abstract of the Disclosure

5        An integrated circuit package(60) has a substrate (12)  
with a first surface (51) for mounting a semiconductor die  
(20) and a second surface (52) defining a via (70). A lead  
(26) is formed by plating a conductive material to project  
outwardly from the second surface. The conductive material  
10 extends from the lead through the first via for coupling to  
the semiconductor die.